

SPECIFICATION FOR APPROVAL

CN: 0

CUSTOMER : _____

PRODUCT TYPE : SMD GLASS SEALING X'TAL 3.2*2.5

NOMINAL FREQ. : 8.000000MHz

TXC P/N : AV08000301

REVISION : A1

CUSTOMER P/N : _____

PM / SALES : _____

DATE : _____

CUSTOMER SIGNATURE & Date _____

- (1) TXC requires one copy returned with signature and title of authorized individual that signifies acceptance of the attached specifications.
- (2) Orders received and accepted by TXC after return of signed copy of specification will be produced per these specifications.
- (3) Any changes to these specifications must be agreed upon by both parties and new revision of the Product Specification Sheet will be issued.
- (4) Any issuance of purchase order prior to consigning back the Approval page of "Specification Sheets" from customers will be regarded as the agreement on the contents of these specifications.

MSL:Level 1
RoHS Compliant

Pb used in sealing glass material is exempt from EU directive

PRODUCT SPECIFICATION SHEET

CN: _____

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PE/RD	QA	MFG
Wen yuan Chang	ZhongLin Wu	Zhi Jun Wu
Wen yuan Chang	ZhongLin Wu	Zhi jun Wu
2-Jan-18	2-Jan-18	2-Jan-18

NOTE:

- (1)The green product standard set by TXC is based upon the international standards. Related information is publicly described on the TXC's Website, and updated regularly. The document is compliant with the latest green product quality system directives at the time.
- (2)Revision "Sx" is for engineering samples only. PE/RD's approval required.
- (3)Revision "Ax" is production ready. PE, QA and MFG's approval required

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[illegible]

Spec Sheet Contents

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ELECTRICAL SPECIFICATIONS

	Parameters	SYM.	Electrical Spec.				Notes
			MIN	TYP	MAX	UNITS	
1	Nominal Frequency	FL	8.000000			MHz	-
2	Oscillation Mode	-	Fundamental			-	-
3	Load Capacitance	CL	12			pF	-
4	Frequency Tolerance	-	±30			ppm	at 25 °C ± 3 °C
5	Frequency Stability	-	±100			ppm	Over Operating Temp. Range (Reference 25°C)
6	Operating Temperature	-	-40	~	125	°C	-
7	Aging	-	±3			ppm	1st Year at 25 °C ± 3 °C
8	Drive Level	DL	-	10	100	uW	-
9	Series Resonant Resistance	Rr	-	-	300	Ω	-
10	Shunt Capacitance	C0	-	-	3	pF	-
11	Insulation Resistance	-	500	-	-	MΩ	at DC 100V
12	Storage Temperature Range	-	-40	~	125	°C	-

Measure equipment

Electrical characteristics measured by S&A250B or equivalent.

Unit Weight:

0.020±0.002 g/pcs

Attention (注意事項) :

1. If you intend to use product on controls relating to medical equipment, aeronautical equipment, aerospace, military science, space equipment, etc.) please do not fail to advise us of your intention beforehand.

請勿將本產品使用在醫療,航空,宇航,軍事或與生命安全性相關的設備中，若需使用在上述應用請事前與TXC聯繫。

2. Crystal units will be damaged by ultrasonic welding process due to resonance of crystal wafer itself.

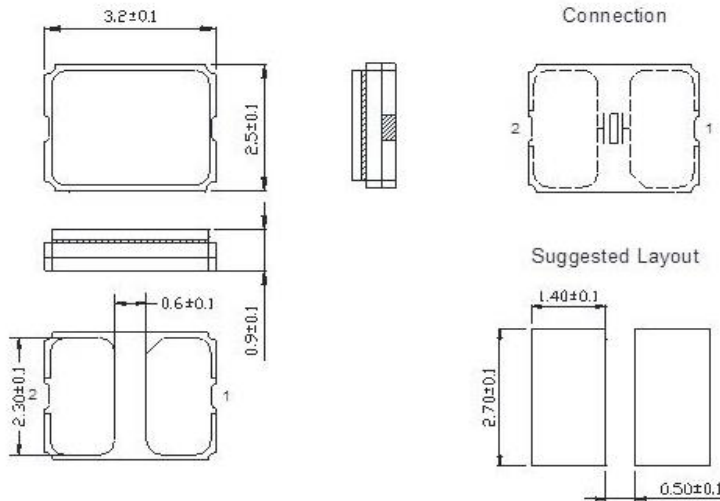
If ultrasonic welding used, TXC strongly recommend verifying damage by ultrasonic weld.

本產品在超音波封合的過程中晶片可能會因共振受損，若有超音波封合需求,TXC強烈建議應給予適當的驗證。

3. Crystal units will be damaged by plastic molding process due to pressure. If plastic molding used, TXC strongly recommend use seam welding products instead.

本產品在熱塑封合的過程中結構可能會受到熱壓力而損壞，若有熱塑封合需求,請給以適當的驗證。

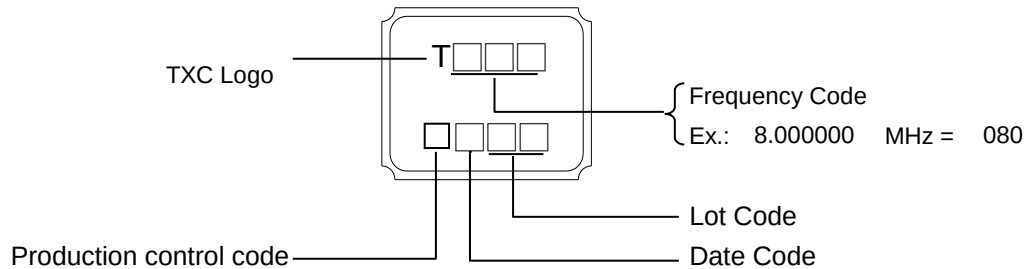
DIMENSION:
(Unit:mm)



*Phrototype, The drawing just for reference only.

*Coplanarity of solderable areas Camber 0.10 mm Max

MARKING



Month Code:

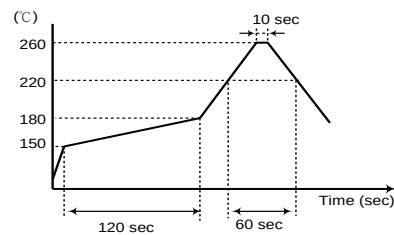
YEAR					MONTH											
					JAN	FEB	MAR	APR	MAY	JUN	JUL	AUG	SEP	OCT	NOV	DEC
2005	2009	2013	2017	2021	A	B	C	D	E	F	G	H	J	K	L	M
2006	2010	2014	2018	2022	N	P	Q	R	S	T	U	V	W	X	Y	Z
2007	2011	2015	2019	2023	a	b	c	d	e	f	g	h	j	k	l	m
2008	2012	2016	2020	2024	n	p	q	r	s	t	u	v	w	x	y	z

*This month code will be cycled every four years

Production Location:China(Ningbo)

SUGGESTED REFLOW PROFILE

Solder melting point :220±10 °C , 60 sec. Min.
Peak Temperature: 260 ± 5 °C , 10 sec. Max.
Reflow passage time : twice



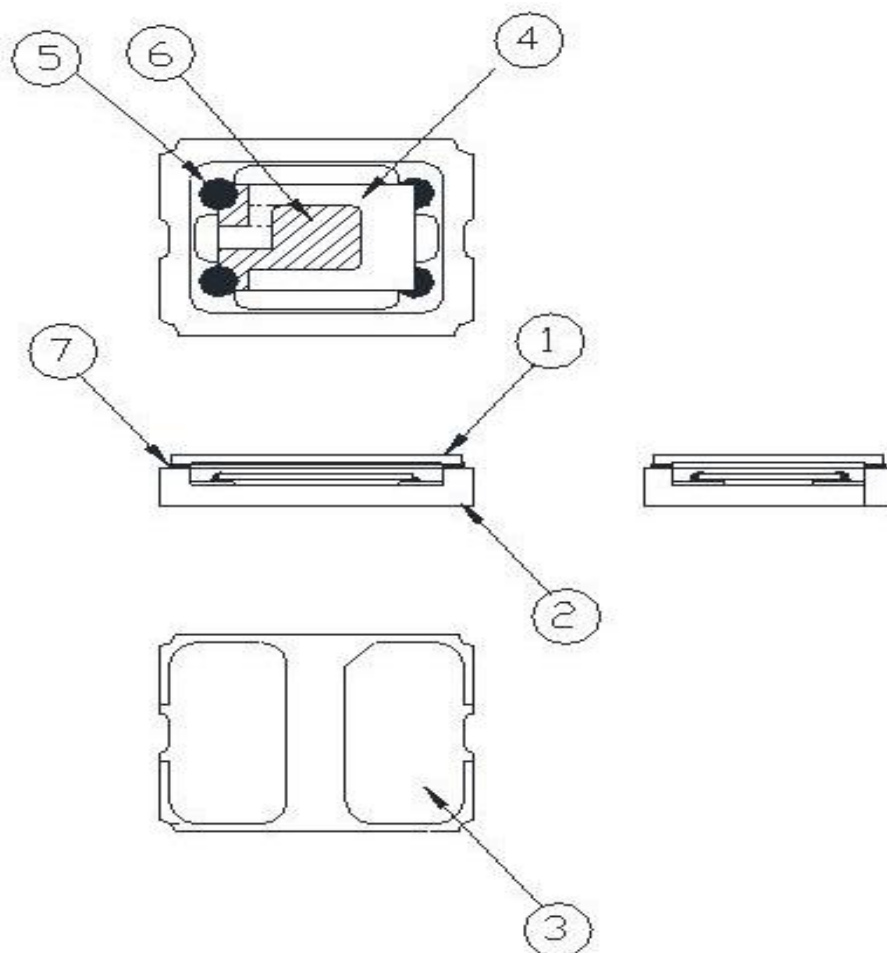
SUGGESTED MANUAL SOLDER CONDITION

Pressing a soliding iron of 350 °C on the terminal electrode for 4 seconds (twice).

When using a soldering iron, press its tip on the part below the sealed part, avoiding glass-sealed part (otherwise, the glass will meit and air-tightness may be lost).

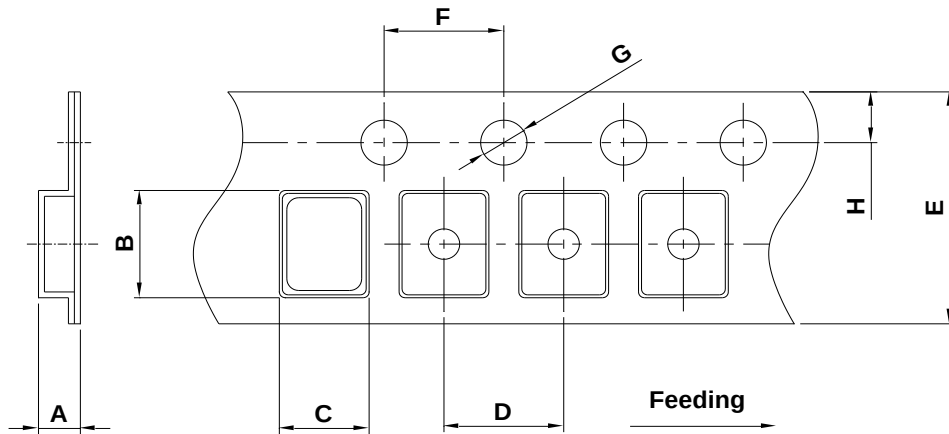
NOTE: After manual welding, the product should be placed at least 2 hours

■ STRUCTURE ILLUSTRATION



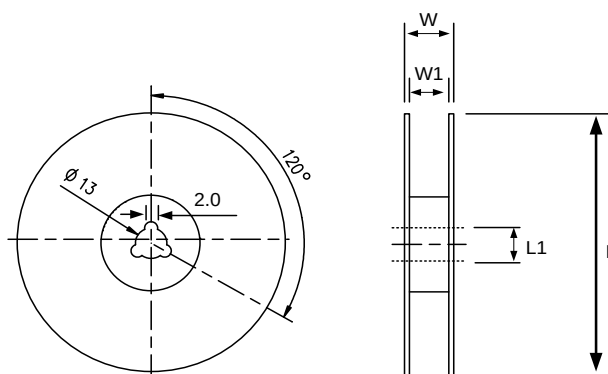
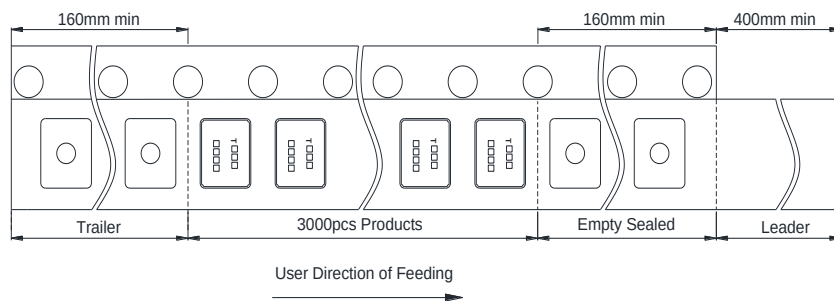
NO	COMPONENTS	MATERIALS	FINISH/SPECIFICATIONS
1	Cap	Ceramic (Al_2O_3)	-
2	Package	Ceramic (Al_2O_3)	-
3	PAD	Au	Tungsten metalize + Ni plating + Au plating
4	Crystal blank	SiO_2	-
5	Conductive adhesive	Resin+Ag	-
6	Electrode	Noble Metal	-
7	Sealing Glass	Glass(PbO)	-

■ EMOSS CARRIER TAPE & REEL



DIMENSIONS	A	B	C	D	E	F	G	H	
	1.65 ±0.10	3.40 ±0.10	2.70 ±0.10	4.00 ±0.10	8.00 ±0.20	4.00 ±0.10	1.55 ±0.10	1.75 ±0.10	(UNIT : mm)

REMARK :



DIMENSIONS	L	L1	W	W1	
	178±1.00	13±0.50	11.5±0.20	8±0.10	(UNIT : mm)

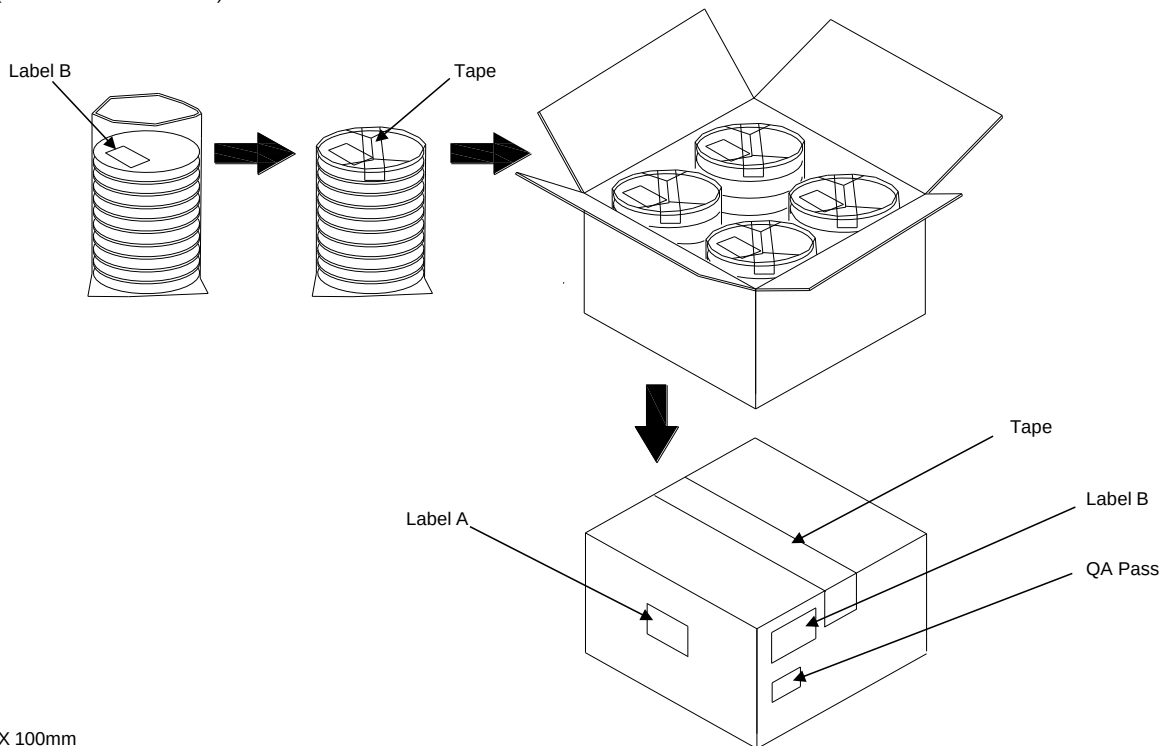
■ PACKING

Reel Quantity :

1. Reel X 6 (6 Reels)
2. Reel X 12 (12 Reels)
3. Reel X 25 (12 Reels + 13 Reels)
4. Reel X 50 (12 Reelsx2 + 13 Reelsx2)

Box Size:

1. L200 X W200 X H140mm
2. L200 X W200 X H250mm
3. L400 X W200 X H250mm
4. L400 X W400 X H280mm



(Label A) Size:100 X 100mm

TXC	
Inv No: 00096815	
Po No: 21106326- 24- 1	
Part No: 00000000	
Qty: 40000 PCS	
C/No: 157- 44	

(Label B) Size:80 X 40mm

TXC CORPORATION		QA PASS
DATE CODE:	00000000	QTY: 0000
LOT NO:	00000000	RoHS HF
PART NO:	00000000	
FREQ:	0000000000	
2011/09/02		

[STORAGE]

1. Don't be caught in the rain.
2. The storage environment shall be 5℃ ~40℃ temperature and 30% ~ 75%RH humidity and free from the sun shine.
3. If customers have special requirements, we can paste labels according to it.

■ RELIABILITY SPECIFICATIONS (AEC-Q200 Compliant)

1.Mechanical Endurance

No.	Test Item	Test Methods	Test Criteria
1.1	Mechanical Shock	2000 G , 0.3 m Sec. ,3 times for all 3 directions.	B C
1.2	Vibration	Frequency range 10 ~ 2000 Hz Acceleration 20G Amplitude 1.52mm Sweep time 20 minute Pendicular axes each test time 4 hours (Total test time 12 hours)	B C
1.3	Terminal Strength	17.7N force for 60sec +/-1sec.	F
1.4	Board Flex	Duration time:60 Sec Minimum,Deviation:3mm	B C
1.5	Solderability	Temperature 245 °C +/- 5°C Immersing depth 0.5 mm minimum Immersion time 5 +/- 0.5 seconds Flux Rosin resin methyl alcohol solvent (1 : 4)	E

2.Environmental Endurance

No.	Test Item	Test Methods	SPEC
2.1	Resistance To Soldering Heat	Test temperature 260 +/- 5 °C Test time 10 +/- 1 sec.	BCD
2.2	High Temp. Storage	+ 125°C ± 3 °C for 1000 ± 12 Hrs	BCD
2.3	Low Temp. Storage	- 40 °C ± 3 °C for 1000 ± 12 Hrs	BCD
2.4	Temperature cycle	-40°C ~125°C ,for 1000 cycles. 	BCD
2.5	Operational Life	1000 hrs @ 125± 3°C. Rated VDD applied with 1 MΩ.	BCD
2.6	High Temp & Humidity	85°C ± 3°C , RH 85% , 1000 Hrs	BCD

RELIABILITY SPECIFICATIONS

Specifications	
A	Frequency change: Within ± 5 ppm or in customer's specification.
B	Frequency change: Within ± 10 ppm or in customer's specification.
C	Equivalent series resistance(E.S.R) change: Within $\pm 15\%$ or 10Ω (larger value).
D	After conditioning , quartz crystal units shall be subjected to standard atmospheric conditions for 24 hour, and measured.
E	Minimum 95% of immersed terminal shall be covered with new uniform solder.
F	No damage on specimen

Measurement condition

Electrical characteristics measured by S&A250B or equivalent.